

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A manufacturing method of a display device comprising:
forming a conductive film over a substrate by ejecting liquid droplets containing conductive particles by using a first liquid droplet ejecting apparatus comprising a liquid droplet ejecting head provided with a plurality of liquid droplet ejecting nozzles arranged linearly;

forming a resist pattern locally on the conductive film by using a second liquid droplet ejecting apparatus comprising a liquid droplet ejecting head provided with a plurality of liquid droplet ejecting nozzles arranged linearly;

forming a wiring by etching the conductive film with the resist pattern as a mask at an atmospheric pressure or a pressure close to the atmospheric pressure by using a first plasma generating device comprising a plurality of pairs of electrodes;

etching the resist pattern at an atmospheric pressure or a pressure close to the atmospheric pressure by using the first plasma generating device;

forming an insulating film over the wiring; and

forming a contact hole by etching the insulating film at ~~[[the]]~~an atmospheric pressure or a pressure close to the atmospheric pressure by using a second plasma generating device provided with a pair of electrodes.

2.-3. (Canceled)

4. (Currently Amended) A manufacturing method of a display device comprising:
forming a conductive film over a substrate by ejecting liquid droplets containing conductive particles by using a liquid droplet ejecting apparatus comprising a liquid droplet ejecting head provided with a plurality of liquid droplet ejecting nozzles arranged linearly;

after forming the conductive film, forming a wiring by etching an unnecessary portion of the conductive film locally at an atmospheric pressure or a pressure close to the atmospheric pressure by using a first plasma generating device comprising a plurality of pairs

of electrodes;

forming an insulating film over the wiring; and

forming a contact hole by etching the insulating film at ~~[[the]]~~an atmospheric pressure or a pressure close to the atmospheric pressure by using a second plasma generating device provided with only a pair of electrodes.

5. (Currently Amended) A manufacturing method of a display device comprising:
forming a conductive film over a substrate by using a liquid droplet ejecting apparatus comprising a liquid droplet ejecting head provided with a plurality of liquid droplet ejecting nozzles arranged linearly;

forming a resist pattern on the conductive film;

after forming the resist pattern, forming a wiring by etching an unnecessary portion of the conductive film locally at an atmospheric pressure or a pressure close to the atmospheric pressure by using a first plasma generating device comprising a plurality of pairs of electrodes;

etching the resist pattern at an atmospheric pressure or a pressure close to the atmospheric pressure by using the first plasma generating device;

forming an insulating film over the wiring; and

forming a contact hole by etching the insulating film at ~~[[the]]~~an atmospheric pressure or a pressure close to the atmospheric pressure by using a second plasma generating device provided with a pair of electrodes.

6. (Currently Amended) ~~[[A]]~~The manufacturing method of a display device according to claim 1, wherein the wiring includes at least one conductive material selected from the group consisting of Ag, Au, Cu, Ni, Pt, Pd, Ir, Rh, W, and Al, metal sulfide of Cd and Zn, oxide of Fe, Ti, Si, Ge, Si, Zr, Ba, and the like, and fine particles or dispersible nanoparticles of silver halide.

7. (Currently Amended) ~~[[A]]~~The manufacturing method of a display device according to claim 4, wherein the wiring includes at least one conductive material selected from the group consisting of Ag, Au, Cu, Ni, Pt, Pd, Ir, Rh, W, and Al, metal sulfide of Cd

and Zn, oxide of Fe, Ti, Si, Ge, Si, Zr, Ba, and the like, and fine particles or dispersible nanoparticles of silver halide.

8. (Currently Amended) ~~[[A]]~~The manufacturing method of a display device according to claim 5, wherein the wiring includes at least one conductive material selected from the group consisting of Ag, Au, Cu, Ni, Pt, Pd, Ir, Rh, W, and Al, metal sulfide of Cd and Zn, oxide of Fe, Ti, Si, Ge, Si, Zr, Ba, and the like, and fine particles or dispersible nanoparticles of silver halide.

9. (Canceled)

10. (Currently Amended) ~~[[A]]~~The manufacturing method of a display device according to claim 1, wherein the pair of electrodes are cylindrical electrodes.

11. (Currently Amended) ~~[[A]]~~The manufacturing method of a display device according to claim 4, wherein the pair of electrodes are cylindrical electrodes.

12. (Currently Amended) ~~[[A]]~~The manufacturing method of a display device according to claim 5, wherein the pair of electrodes are cylindrical electrodes.

13.-14. (Canceled)

15. (Previously Presented) The manufacturing method of a display device according to claim 1, wherein the plurality of pairs of electrodes are arranged linearly.

16. (Previously Presented) The manufacturing method of a display device according to claim 4, wherein the plurality of pairs of electrodes are arranged linearly.

17. (Previously Presented) The manufacturing method of a display device according to claim 5, wherein the plurality of pairs of electrodes are arranged linearly.

18. (Previously Presented) The manufacturing method of a display device according to claim 1, wherein the insulating film comprising at least one selected from the group consisting of a silicon nitride, a silicon oxide and an organic resin.

19. (Previously Presented) The manufacturing method of a display device according to claim 4, wherein the insulating film comprising at least one selected from the group consisting of a silicon nitride, a silicon oxide and an organic resin.

20. (Previously Presented) The manufacturing method of a display device according to claim 5, wherein the insulating film comprising at least one selected from the group consisting of a silicon nitride, a silicon oxide and an organic resin.